

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	184	"204".clas. and (composite target)	US-PGPUB; USPAT	ADJ	ON	2007/08/03 15:34
L2	2	"204".clas. and ((composite target) with (equal or proportional or equivalent))	US-PGPUB; USPAT	ADJ	ON	2007/08/03 15:34
S1	2	((("6305067") or ("6570085")).PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:57
S2	112	"204".clas. and substrate and plating and (nickel or Ni) and (copper or Cu) and steel and target and sputter	US-PGPUB; USPAT	ADJ	ON	2007/03/21 17:18
S3	2002	"204".clas. and target and sputtering adj apparatus	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:55
S4	350	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:56
S5	170	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:56
S6	142	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon	US-PGPUB; USPAT	ADJ	ON	2007/03/22 12:03
S7	0	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon and (electically conductive layer)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:58
S8	4	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon and (electrically conductive layer)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:58
S9	2887	kulkarni	US-PGPUB; USPAT	ADJ	ON	2007/03/22 11:50
S10	1	("6283357").PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:50
S11	1	("5593551").PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:57

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S12	105	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (power density)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 12:33
S13	103	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and resin	US-PGPUB; USPAT	ADJ	ON	2007/03/22 14:05
S14	12	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (power density) and resin	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:03
S15	0	"204".clas. and target and sputtering adj apparatus and substrate and resin and polystyrene	US-PGPUB; USPAT	ADJ	ON	2007/03/22 13:39
S16	31	"204".clas. and target and sputtering adj apparatus and substrate and resin and polystyrene	US-PGPUB; USPAT	ADJ	ON	2007/03/22 13:39
S17	22	"204".clas. and composite target and sputtering adj apparatus and substrate and vacuum adj chamber	US-PGPUB; USPAT	ADJ	ON	2007/03/22 14:05
S18	516	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (voltage or volt)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:03
S19	95	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (voltage or volt) and (power density)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:05
S20	20	electromagnet shield	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:10
S21	3368	electromagnet shield	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:11
S22	0	(electromagnet shield) and power and volt	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:11
S23	183	(electromagnet shield) and power	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:13
S24	2	(electromagnet shield) and volt	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:11

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S25	12	(electromagnet shield) and power and pressure	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:11
S26	1	2007-105519.NRAN.	DERWENT	ADJ	ON	2007/07/25 14:12
S27	15326	(electromagnet shield) or (EMI)	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:14
S28	5100	(electromagnet shield) or (EMI) and power	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:14
S29	3390	(electromagnet shield) or (EMI) and power and volt	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:14
S30	3369	(electromagnet shield) or (EMI) and power and volt and pressure	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:14
S31	3368	(electromagnet shield) or (EMI) and power and volt and pressure and sputter	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:14
S32	3368	(electromagnet shield) or (EMI) and power and volt and pressure and sputter and SCCM	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:15
S33	3368	(electromagnet shield) or (EMI) and power and volt and pressure and sputter and SCCM and target and (nickel or ni) and (copper or cu) and (stainless steel)	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:16
S34	3368	(electromagnet shield) or (EMI) and power and volt and pressure and sputter and SCCM and target and (nickel or ni) and (copper or cu) and (stainless steel) and (plurality or composite or multiple with (target))	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:20
S35	28	(electromagnet shield) or (EMI) and power and volt and pressure and sputter and SCCM and target and (nickel or ni) and (copper or cu) and (stainless steel) and (plurality or composite or multiple with (target))	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:38
S36	0	((electromagnet shield) or (EMI)) and power and volt and pressure and sputter and SCCM and target and (nickel or ni) and (copper or cu) and (stainless steel) and (plurality or composite or multiple with (target))	EPO; JPO; DERWENT	ADJ	ON	2007/07/25 14:20
S37	6075	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel)	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:45

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S38	3711	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel) and power	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:46
S39	820	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel) and power and volt	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:46
S40	34	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel) and power and volt and (substrate with resin)	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:49
S41	633	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel) and power and volt and pressure	US-PGPUB; USPAT	ADJ	ON	2007/07/25 14:49
S42	114	((composite or plural or multi) with target) and (copper or cu or nickel or ni or steel) and power and volt and pressure and SCCM	US-PGPUB; USPAT	ADJ	ON	2007/07/26 10:11
S43	1219	targets and (copper or cu or nickel or ni or steel) and power and volt and pressure and SCCM	US-PGPUB; USPAT	ADJ	ON	2007/07/25 16:56
S44	12813	targets with (copper or cu or nickel or ni or steel)	US-PGPUB; USPAT	ADJ	ON	2007/07/25 16:56
S45	2669	magnetron and vacuum and power and volt	US-PGPUB; USPAT	ADJ	ON	2007/07/25 16:56
S46	398	S44 and S45	US-PGPUB; USPAT	ADJ	ON	2007/07/25 16:57
S48	2638	sequential deposition	US-PGPUB; USPAT	ADJ	ON	2007/07/25 17:06
S49	2870	(sequential or consecutive) deposition	US-PGPUB; USPAT	ADJ	ON	2007/07/25 17:06
S50	297	((sequential or consecutive) deposition) and sputter and target and substrate	US-PGPUB; USPAT	ADJ	ON	2007/07/25 17:07
S51	57	((sequential or consecutive) deposition) and sputter and substrate and (target with (copper or cu or nickel or ni or steel))	US-PGPUB; USPAT	ADJ	ON	2007/07/25 17:49
S52	16	((sequential or consecutive) deposition) and sputter and substrate and (target with conductive)	US-PGPUB; USPAT	ADJ	ON	2007/07/25 17:50
S53	4	(("6585870") or ("6518086") or ("6593150") or ("4923585")).PN.	US-PGPUB; USPAT	OR	OFF	2007/07/26 10:11
S54	1	("4465575").PN.	US-PGPUB; USPAT	OR	OFF	2007/07/26 10:41

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S55	427	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe)))	US-PGPUB; USPAT	ADJ	ON	2007/07/26 12:20
S56	154	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe))) and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/07/26 12:20
S57	24	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe))) and "204".clas. and (dc magnetron)	US-PGPUB; USPAT	ADJ	ON	2007/07/26 12:27
S58	129	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe)))	EPO; JPO; DERWENT	ADJ	ON	2007/07/26 12:27
S59	0	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe))) and dc magnetron	EPO; JPO; DERWENT	ADJ	ON	2007/07/26 12:27
S60	9	target with ((ni or nickel) and (copper or cu) and (steel or ((chromium or cr) and iron or fe))) and magnetron	EPO; JPO; DERWENT	ADJ	ON	2007/07/26 12:27
S61	3	((("20030177949") or ("6676741") or ("5711824"))).PN.	US-PGPUB; USPAT	OR	OFF	2007/07/31 10:10
S62	3	jp-63270452-\$.did. or kr-2002075643-\$.did.	EPO; JPO; DERWENT	ADJ	ON	2007/07/31 20:53
S63	69	((DC or (direct current)) adj magnetron) and (power density) and (volt or vdc) and sputter and target and substrate and "204". clas.	US-PGPUB; USPAT	ADJ	ON	2007/07/31 20:57
S64	2	((DC or (direct current)) adj magnetron) and (power density) and (volt or vdc) and sputter and target and "204".clas. and (copper or cu or nickel or ni or indium or in or cr or chromium) and (substrate with resin)	US-PGPUB; USPAT	ADJ	ON	2007/07/31 20:58